



## Professional High Voltage Thin Film MELF Resistors



MMA 0204 HV and MMB 0207 HV professional thin film MELF resistors are the perfect choice for most fields of modern professional electronics where reliability and stability is of major concern. The typical applications in the fields of lighting and medical equipment reflect the outstanding level of proven reliability.

### FEATURES

- High operating voltage,  $U_{max.} = 1000\text{ V}$
- Advanced metal film technology
- Matte Sn termination on Ni barrier layer
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**  
**GREEN**  
(5-2008)

### APPLICATIONS

- Lighting
- Industrial
- Medical equipment

TECHNICAL SPECIFICATIONS			
DESCRIPTION	MMA 0204 HV	MMB 0207 HV	
DIN size	0204	0207	
Metric CECC size	RC 3715M	RC 6123M	
Resistance range	340 kΩ to 10 MΩ	340 kΩ to 10 MΩ	
Resistance tolerance	± 1 %	± 1 %	
Temperature coefficient	± 50 ppm/K	± 50 ppm/K	
Voltage coefficient	TBD	TBD	
Rated dissipation, $P_{70}^{(1)}$	0.4 W	1.0 W	
Operating voltage, $U_{max. AC/DC}$	500 V	1000 V	
Operating temperature range	-55 °C to 155 °C	-55 °C to 155 °C	
Permissible voltage against ambient (insulation):			
	1 min, $U_{ins}$	300 V	500 V
	Continuous	75 V	75 V

#### Note

(1) Please refer to APPLICATION INFORMATION below.

### APPLICATION INFORMATION

The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat flow support of the printed-circuit board (thermal resistance). The rated dissipation applies only if the permitted film temperature is not exceeded. Furthermore, a high level of ambient temperature or of power dissipation may raise the temperature of the solder joint, hence special solder alloys or board materials may be required to maintain the reliability of the assembly. The applicable voltage is limited by maximum power.

These resistors do not feature a limited lifetime when operated within the permissible limits. However, resistance value drift increasing over operating time may result in exceeding a limit acceptable to the specific application, thereby establishing a functional lifetime. At the maximum permissible film temperature of 155 °C the useful lifetime is specified for 8000 h. The designer may estimate the performance of the particular resistor application or set certain load and temperature limits in order to maintain a desired stability.



MAXIMUM RESISTANCE CHANGE AT RATED DISSIPATION			
OPERATION MODE		STANDARD	POWER
Rated dissipation, $P_{70}$	MMA 0204 HV	0.25 W	0.4 W
	MMB 0207 HV	0.4 W	1.0 W <sup>(1)</sup>
Operating temperature range		-55 °C to 125 °C	-55 °C to 155 °C
Permissible film temperature, $\theta_F$ max.		125 °C	155 °C
Max. resistance change at $P_{70}$ for resistance range, $\Delta R/R$ after:	MMA 0204 HV	340 k $\Omega$ to 10 M $\Omega$	340 k $\Omega$ to 10 M $\Omega$
	MMB 0207 HV	340 k $\Omega$ to 10 M $\Omega$	340 k $\Omega$ to 10 M $\Omega$
	1000 h	$\leq 0.5 \%$	$\leq 1 \%$
	8000 h	$\leq 1 \%$	$\leq 2 \%$

**Note**

<sup>(1)</sup> Specified power rating requires dedicated heat sink pads.

TEMPERATURE COEFFICIENT AND RESISTANCE RANGE				
TYPE/SIZE	TCR	TOLERANCE	RESISTANCE	E-SERIES
MMA 0204 HV	$\pm 50$ ppm/K	$\pm 1 \%$	340 k $\Omega$ to 10 M $\Omega$	E24; E96
MMB 0207 HV	$\pm 50$ ppm/K	$\pm 1 \%$	340 k $\Omega$ to 10 M $\Omega$	E24; E96

PACKAGING						
TYPE/SIZE	CODE	QUANTITY	CARRIER TAPE	WIDTH	PITCH	REEL DIAMETER
MMA 0204 HV	B3 = BL	3000	Antistatic blister tape acc. IEC 60286-3 Type 2a	8 mm	4 mm	180 mm/7"
	B0	10 000				330 mm/13"
MMB 0207 HV	B2	2000	Antistatic blister tape acc. IEC 60286-3 Type 2a	12 mm	4 mm	180 mm/7"
	B7	7000				330 mm/13"

**PART NUMBER AND PRODUCT DESCRIPTION**

Part Number: **MMB0207MC3324FB200**

M	M	B	0	2	0	7	M	C	3	3	2	4	F	B	2	0	0
TYPE/SIZE		VERSION		TCR		RESISTANCE			TOLERANCE		PACKAGING						
MMA0204 MMB0207		M = HV		C = $\pm 50$ ppm/K		3 digit value 1 digit multiplier			F = $\pm 1 \%$		B3 B0 B2 B7						
						MULTIPLIER											
						3 = $\cdot 10^3$											
						4 = $\cdot 10^4$											
						5 = $\cdot 10^5$											

Product Description: **MMB 0207 -50 1 % HV B2 3M32**

MMB	0207	- 50	1 %	HV	B2	3M32
TYPE	SIZE	TCR	TOLERANCE	HIGH VOLTAGE	PACKAGING	RESISTANCE
MMA MMB	0204 0207	$\pm 50$ ppm/K	$\pm 1 \%$		BL B0 B2 B7	3M32 = 3.32 M $\Omega$

**Note**

• Products can be ordered using either the PART NUMBER or the PRODUCT DESCRIPTION.



## DESCRIPTION

Production is strictly controlled and follows an extensive set of instructions established for reproducibility. A homogeneous film of metal alloy is deposited on a high grade ceramic body ( $Al_2O_3$ ) and conditioned to achieve the desired temperature coefficient. Nickel plated steel termination caps are firmly pressed on the metallised rods. A special laser is used to achieve the target value by smoothly cutting a helical groove in the resistive layer without damaging the ceramics. The resistor elements are covered by a protective coating designed for electrical, mechanical and climatic protection. The terminations receive a final pure tin on nickel plating. Four or five colour code rings designate the resistance value and tolerance in accordance with **IEC 60062** <sup>(1)</sup>.

The result of the determined production is verified by an extensive testing procedure performed on 100 % of the individual resistors. This includes full screening for the elimination of products with a potential risk of early field failures according to EN 140401-803, 2.1.2.2. Only accepted products are laid directly into the blister tape in accordance with **IEC 60286-3, Type 2a** <sup>(1)</sup> or bulk case in accordance with **IEC 60286-6** <sup>(1)</sup>.

## ASSEMBLY

The resistors are suitable for processing on automatic SMD assembly systems. They are suitable for automatic soldering using wave, reflow or vapour phase as shown in **IEC 61760-1** <sup>(1)</sup>. The encapsulation is resistant to all cleaning solvents commonly used in the electronics industry, including alcohols, esters and aqueous solutions. The suitability of conformal coatings, if applied, shall be qualified by appropriate means to ensure the long-term stability of the whole system.

The resistors are completely lead (Pb)-free, the pure tin plating provides compatibility with lead (Pb)-free and lead containing soldering processes. Solderability is specified for 2 years after production or requalification, however, excellent solderability is proven after extended storage in excess of 10 years. The permitted storage time is 20 years. The immunity of the plating against tin whisker growth has been proven under extensive testing.

All products comply with the **JIG 101** list of legal restrictions on hazardous substances.

This includes full compliance with the following directives:

- 2000/53/EC End of Life Vehicle Directive (ELV) and Annex II (ELV II)
- 2011/65/EU Restriction of the use of Hazardous Substances Directive (RoHS)
- 2012/19/EU Waste Electrical and Electronic Equipment Directive (WEEE)

## APPROVALS

Vishay Beyschlag has achieved “**Approval of Manufacturer**” in accordance with **IECQ 03-1**. The release certificate for “**Technology Approval Schedule**” in accordance with **CECC 240001** based on **IECQ 03-3-1** is granted for the Vishay Beyschlag manufacturing process.

## RELATED PRODUCTS

For products with professional specification see the datasheet:

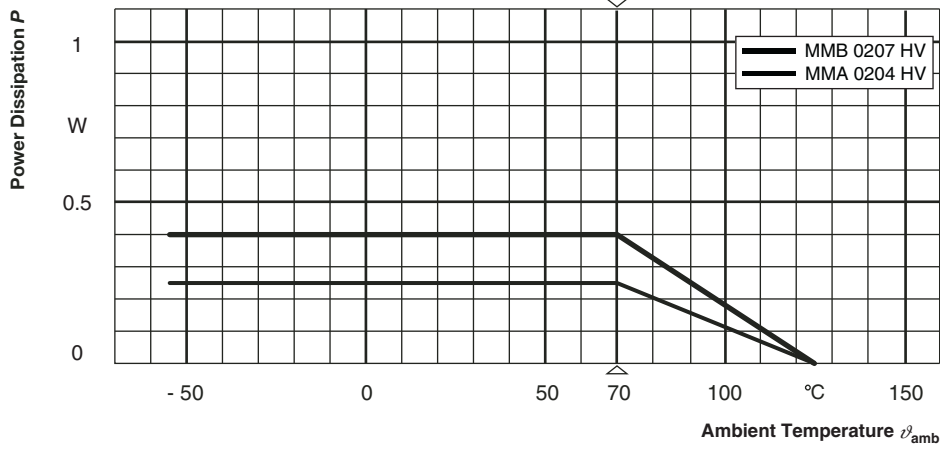
- “Professional Thin Film MELF Resistors” ([www.vishay.com/doc?28713](http://www.vishay.com/doc?28713))

## Note

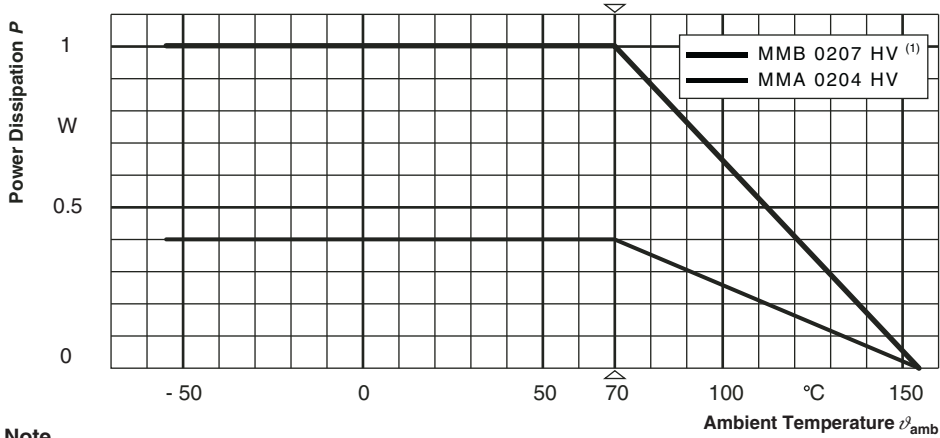
<sup>(1)</sup> The quoted IEC standards are also released as EN standards with the same number and identical contents.



**FUNCTIONAL PERFORMANCE**



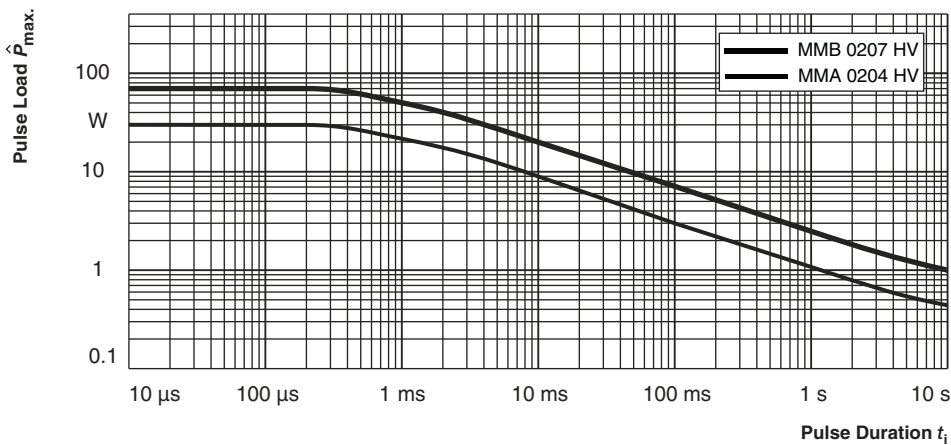
**Derating - Standard Operation**



**Note**

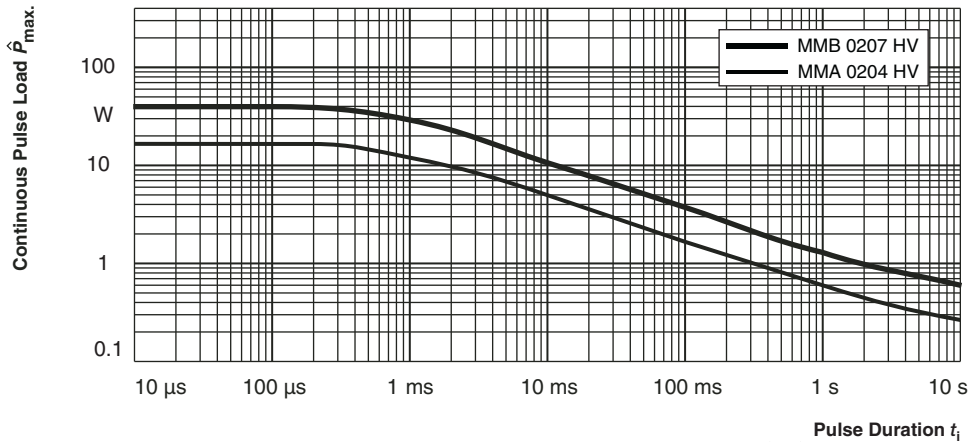
(1) Specified power rating requires dedicated heat sink pads

**Derating - Power Operation**



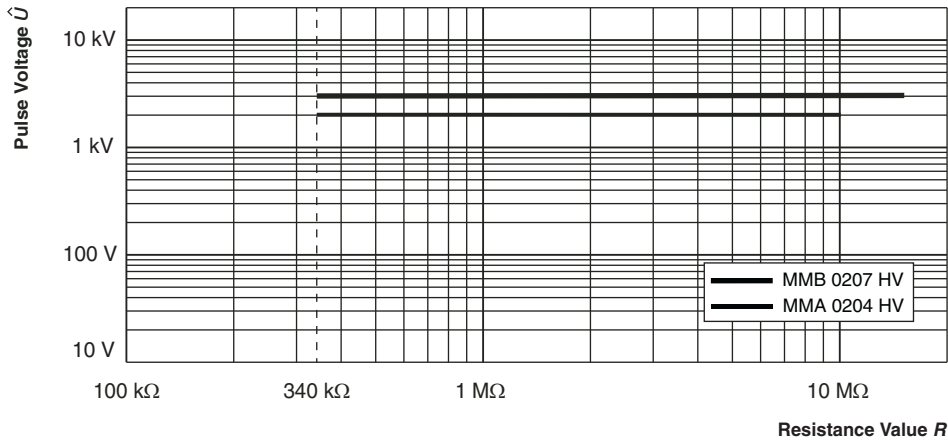
**Single Pulse**

Maximum pulse load, single pulse; applicable if  $\bar{P} \rightarrow 0$  and  $n \leq 1000$  and  $\hat{U} \leq \hat{U}_{max}$ ; for permissible resistance change equivalent to 8000 h operation in power operation mode



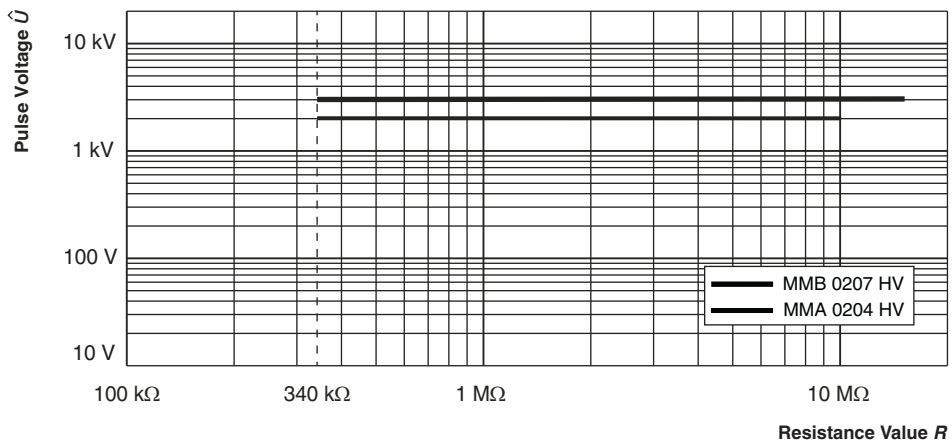
Maximum pulse load, continuous pulses; applicable if  $\bar{P} \leq P(\vartheta_{amb})$  and  $\hat{U} \leq \hat{U}_{max}$ ; for permissible resistance change equivalent to 8000 h operation in power operation mode

### Continuous Pulse



Pulse load rating in accordance with IEC 60 115-1, 4.27; 1.2  $\mu$ s/50  $\mu$ s; 5 pulses at 12 s intervals; for permissible resistance change  $(0.5 \% \times R + 0.05 \Omega)$

### 1.2/50 Pulse



Pulse load rating in accordance with IEC 60115-1, 4.27; 10  $\mu$ s/700  $\mu$ s; 10 pulses at 1 minute intervals; for permissible resistance change  $(0.5 \% \times R + 0.05 \Omega)$

### 10/700 Pulse



**TESTS AND REQUIREMENTS**

All tests are carried out in accordance with the following specifications:

- EN 60115-1, generic specification
- EN 60115-8 (successor of EN 140400), sectional specification
- EN 140401-803, detail specification
- IEC 60068-2-xx, test methods

The parameters stated in the Test Procedures and Requirements table are based on the required tests and permitted limits of EN 140401-803. The table presents only the most important tests, for the full test schedule refer to the documents listed above. However, some additional tests and a number of improvements against those minimum requirements have been included.

The testing also covers most of the requirements specified by EIA/ECA-703 and JIS-C-5201-1.

The tests are carried out under standard atmospheric conditions in accordance with IEC 60068-1, 4.3, whereupon the following values are applied:

- Temperature: 15 °C to 35 °C
- Relative humidity: 45 % to 75 %
- Air pressure: 86 kPa to 106 kPa (860 mbar to 1060 mbar).

A climatic category LCT/UCT/56 is applied, defined by the lower category temperature (LCT), the upper category temperature (UCT), and the duration of exposure in the damp heat, steady state test (56 days).

The components are mounted for testing on printed circuit boards in accordance with EN 60115-8, 2.4.2, unless otherwise specified.

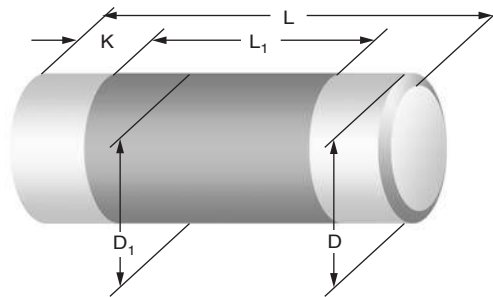
TEST PROCEDURES AND REQUIREMENTS					
EN 60115-1 CLAUSE	IEC 60068-2 <sup>(1)</sup> TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE ( $\Delta R$ )	
			Stability for product types:	<b>STABILITY CLASS 0.25 OR BETTER</b>	<b>STABILITY CLASS 2 OR BETTER</b>
			<b>MMA 0204 HV</b>	-	> 340 k $\Omega$
			<b>MMB 0207 HV</b>	340 k $\Omega$ to 1 M $\Omega$	> 1 M $\Omega$
4.5	-	Resistance	-	$\pm 1 \% R$	$\pm 1 \% R$
4.8.4.2	-	Temperature coefficient	At (20/-55/20) °C and (20/125/20) °C	$\pm 50$ ppm/K	
4.25.1	-	Endurance at 70 °C: Standard operation mode	$U = \sqrt{P_{70}} \times R \leq U_{max.};$ 1.5 h on; 0.5 h off; 70 °C; 1000 h 70 °C; 8000 h	$\pm (0.15 \% R + 10 \text{ m}\Omega)$ $\pm (0.3 \% R + 10 \text{ m}\Omega)$	$\pm (0.5 \% R + 10 \text{ m}\Omega)$ $\pm (1 \% R + 10 \text{ m}\Omega)$
	-	Endurance at 70 °C: Power operation mode	$U = \sqrt{P_{70}} \times \bar{R} \leq U_{max.};$ 1.5 h on; 0.5 h off; 70 °C; 1000 h 70 °C; 8000 h	$\pm (0.3 \% R + 10 \text{ m}\Omega)$ $\pm (1 \% R + 10 \text{ m}\Omega)$	$\pm (1 \% R + 10 \text{ m}\Omega)$ $\pm (2 \% R + 10 \text{ m}\Omega)$
4.25.3	-	Endurance at upper category temperature	125 °C; 1000 h	$\pm (0.15 \% R + 5 \text{ m}\Omega)$	$\pm (1 \% R + 5 \text{ m}\Omega)$
			155 °C; 1000 h	$\pm (0.3 \% R + 5 \text{ m}\Omega)$	$\pm (2 \% R + 5 \text{ m}\Omega)$
4.24	78 (Cab)	Damp heat, steady state	(40 $\pm$ 2) °C; 56 days; (93 $\pm$ 3) % RH	$\pm (0.15 \% R + 10 \text{ m}\Omega)$	$\pm (1 \% R + 10 \text{ m}\Omega)$
-	1 (Ab)	Cold	-55 °C; 2 h	$\pm (0.05 \% R + 5 \text{ m}\Omega)$	$\pm (0.1 \% R + 5 \text{ m}\Omega)$
4.19	14 (Na)	Rapid change of temperature	30 min at LCT; 30 min at UCT; LCT = -55 °C; UCT = 155 °C 1000 cycles	$\pm (0.25 \% R + 10 \text{ m}\Omega)$	$\pm (0.5 \% R + 10 \text{ m}\Omega)$



TEST PROCEDURES AND REQUIREMENTS					
EN 60115-1 CLAUSE	IEC 60068-2 <sup>(1)</sup> TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE ( $\Delta R$ )	
			Stability for product types:	<b>STABILITY CLASS 0.25 OR BETTER</b>	<b>STABILITY CLASS 2 OR BETTER</b>
			<b>MMA 0204 HV</b>	-	> 340 k $\Omega$
			<b>MMB 0207 HV</b>	340 k $\Omega$ to 1 M $\Omega$	> 1 M $\Omega$
4.13	-	Short time overload: Standard operation mode	$U = 2.5 \times \sqrt{P_{70} \times R}$ $\leq 2 \times U_{max.};$ 5 s	$\pm (0.03 \% R + 5 \text{ m}\Omega)$	$\pm (0.15 \% R + 5 \text{ m}\Omega)$
		Short time overload: Power operation mode		$\pm (0.05 \% R + 5 \text{ m}\Omega)$	$\pm (0.15 \% R + 5 \text{ m}\Omega)$
4.22	6 (Fc)	Vibration	Endurance by sweeping; 10 Hz to 2000 Hz; no resonance; amplitude $\leq 1.5 \text{ mm}$ or $\leq 200 \text{ m/s}^2$ ; 7.5 h	$\pm (0.05 \% R + 5 \text{ m}\Omega)$	$\pm (0.1 \% R + 5 \text{ m}\Omega)$
4.40	-	Electrostatic discharge (Human Body Model)	IEC 61340-3-1 <sup>(1)</sup> ; 3 pos. + 3 neg. discharges MMA 0204 HV: 2 kV MMB 0207 HV: 4 kV	$\pm (0.5 \% R + 50 \text{ m}\Omega)$	
4.17.2	58 (Td)	Solderability	Solder bath method; SnPb40; non-activated flux; (215 $\pm$ 3) °C; (3 $\pm$ 0.3) s	Good tinning ( $\geq 95 \%$ covered); no visible damage	
			Solder bath method; SnAg3Cu0.5 or SnAg3.5; non-activated flux; (235 $\pm$ 3) °C; (2 $\pm$ 0.2) s	Good tinning ( $\geq 95 \%$ covered); no visible damage	
4.18.2	58 (Td)	Resistance to soldering heat	Solder bath method; (260 $\pm$ 5) °C; (10 $\pm$ 1) s	$\pm (0.05 \% R + 10 \text{ m}\Omega)$	$\pm (0.25 \% R + 10 \text{ m}\Omega)$
			Reflow method 2 (IR/forced gas convection); (260 $\pm$ 5) °C; (10 $\pm$ 1) s	$\pm (0.02 \% R + 10 \text{ m}\Omega)$	$\pm (0.1 \% R + 10 \text{ m}\Omega)$
4.29	45 (XA)	Component solvent resistance	Isopropyl alcohol; 50 °C; method 2	No visible damage	
4.30	45 (XA)	Solvent resistance of marking	Isopropyl alcohol; 50 °C; method 1, toothbrush	Marking legible; no visible damage	
4.32	21 (Ue <sub>3</sub> )	Shear (adhesion)	45 N	No visible damage	
4.33	21 (Ue <sub>1</sub> )	Substrate bending	Depth 2 mm, 3 times	No visible damage, no open circuit in bent position $\pm (0.05 \% R + 10 \text{ m}\Omega)$	
4.7	-	Voltage proof	$U_{RMS} = U_{ins}$ ; 60 s	No flashover or breakdown	
4.35	-	Flammability	IEC 60695-11-5 <sup>(1)</sup> , needle flame test; 10 s	No burning after 30 s	

**Note**

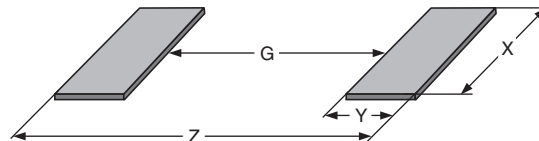
<sup>(1)</sup> The quoted IEC standards are also released as EN standards with the same number and identical contents.

**DIMENSIONS**


DIMENSIONS AND MASS						
TYPE	L (mm)	D (mm)	L <sub>1</sub> min. (mm)	D <sub>1</sub> (mm)	K (mm)	MASS (mg)
MMA 0204 HV	3.6 + 0/- 0.2	1.4 + 0/- 0.1	1.8	D + 0/- 0.15	0.8 ± 0.1	22
MMB 0207 HV	5.8 + 0/- 0.15	2.2 + 0/- 0.2	3.2	D + 0/- 0.2	1.15 ± 0.1	80

**Note**

- Color code marking is applied according to IEC 60062 <sup>(1)</sup> in four bands (E24 series) or five bands (E96 series). Each color band appears as a single solid line, voids are permissible if at least 2/3 of the band is visible from each radial angle of view. The last color band for tolerance is approximately 50 % wider than the other bands. An interrupted violet band between the 3<sup>rd</sup> and 4<sup>th</sup> full band identifies the special high voltage type.

**PATTERN STYLES FOR MELF RESISTORS**


RECOMMENDED SOLDER PAD DIMENSIONS								
TYPE	WAVE SOLDERING				REFLOW SOLDERING			
	G (mm)	Y (mm)	X (mm)	Z (mm)	G (mm)	Y (mm)	X (mm)	Z (mm)
MMA 0204 HV	1.5	1.5	1.8	4.5	1.7	1.2	1.6	4.1
MMB 0207 HV	2.8	2.1	2.6	7.0	3.2	1.7	2.4	6.6

**Notes**

- The rated dissipation applies only if the permitted film temperature is not exceeded. Furthermore, a high level of ambient temperature or of power dissipation may raise the temperature of the solder joint, hence special solder alloys or board materials may be required to maintain the reliability of the assembly. Specified power rating above 125 °C requires dedicated heat-sink pads, which to a great extent depend on board materials and design. The given solder pad dimensions reflect the considerations for board design and assembly as outlined e.g. in standards IEC 61188-5-x <sup>(1)</sup>, or in publication IPC-7351. They do not guarantee any supposed thermal properties, particularly as these are also strongly influenced by many other parameters.

Still, the given solder pad dimensions will be found adequate for most general applications, e.g. those referring to “standard operation mode”. Please note however that applications for “power operation mode” require special considerations for the design of solder pads and adjacent conductor areas.

<sup>(1)</sup> The quoted IEC standards are also released as EN standards with the same number and identical contents.





## Disclaimer

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Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

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## Material Category Policy

**Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.**

**Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.**

**Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.**



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

**Телефон:** 8 (812) 309 58 32 (многоканальный)

**Факс:** 8 (812) 320-02-42

**Электронная почта:** [org@eplast1.ru](mailto:org@eplast1.ru)

**Адрес:** 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.